

TA3000 Thermally Conductive Adhesive



BENEFITS AND FEATURES

- One part material, moisture cure
- Silicone base
- Good thermal performance
- Good Adhesion, avoid slot and screws
- Low viscosity before curing, adjust to irregular surfaces

OVERVIEW

Honeywell TA series Thermally Conductive Adhesive products form a curable adhesion layer between two surfaces with a little pressure and meanwhile offers good heat dissipation effect in use across multitude of applications. TA3000 is a one-part moisture cured silicone thermally conductive adhesive material, which would bond the heat generating component with heat sink when exposure to moisture in the air. The cured material could function as excellent heat transfer media, fixing of electronic components and sealing protection against contaminants at the same time during application.

TYPICAL APPLICATIONS

- PCBA
- LED assemblies
- Automotive electronics
- Power units

Storage & Use

- Manual or automatic dispense
- Cure at room temperature with 10 to 80% RH
- Suggest not used for highly confined or deep section space
- Seal up and store in a cool, dry place after each use

Property	Test Method	Unit	TA3000
Appearance	Visual	-	White
Specific Gravity	ASTM D792	g/cm ³	2.8
Viscosity (25 °C, d=2 sec ⁻¹ , 0.5mm)	Brookfield Viscometer	Pa.s	440
Hardness (cured)	ASTM D2240	Shore A	75
Thermal Conductivity	ASTM D5470	W/m·K	3.0
CTE linear	TMA	ppm/°C	102
Tack free time (25 °C, 50% RH)		min	10~20
Unprimed lap-shear strength (Al, Al)	DIN EN 1465	N/mm ²	1.0

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